AMENDMENTS TO THE CLAIMS

- 1. (Cancelled)
- (Currently amended) A composite article comprising a silicone rubber matrix reinforced with polyaramid textile, wherein said polyaramid textile is a weft insertion warp knit fabric having polyaramid weft and/or warp yarns, said polyaramid textile being bonded to said silicone rubber by means of a bonding composition, said bonding composition comprising an acryloxy organosilane, after said polyaramid textile has been activated with at least one of an epoxy compound and a plasma.
- (Previously presented) A composite article according to claim 2 in which the polyaramid is a p-phenylene polyaramid.
- 4. (Previously presented) A composite article according to claim 2 in which said bonding composition further comprises an epoxy organosilane.
- (Original) A composite article according to claim 4 in which said bonding composition further comprises a vinyl organosilane.
- 6. (Previously presented) A composite article according to claim 2 in which said organosilane is a trimethoxy silane.

- 7. (Previously presented) A composite article according to claim 2 in which said polyaramid textile comprises polyaramid single end or cabled cords.
- 8. (Cancelled)
- 9. (Currently amended) A process for manufacturing a polyaramid reinforced silicone rubber article comprising the steps of:
 - a) selecting a polyaramid textile, the polyaramid textile being a weft insertion warp knit fabric having polyaramid weft and/or warp yarns,
 - b) activating the polyaramid textile with at least one of an epoxy compound and a plasma,
 - c) dipping the polyaramid textile into an organosilane dip comprising acryloxy organosilane, and
 - d) bonding the dipped polyaramid textile to silicone rubber.
- (Original) A process according to claim 9 wherein said organosilane dip further comprises an epoxy organosilane.
- 11. (Original) A process according to claim 9 wherein said organosilane dip is an aqueous dip.
- 12. (Currently amended) A process according to claim 9 in which the polyaramid textile is activated with an epoxy compound, such epoxy activation is—being followed by plasma activation, which is, in turn, followed by the organosilane dipping step.

- 13. (Original) A process according to claim 12 in which said plasma activation comprises an air plasma.
- 14. (Original) A process according to claim 13 in which said plasma activation comprises an air plasma further including water as an aerosol.
- 15. (Original) A process according to claim 9 in which said organosilane dip further comprises an amino functional organosilane.
- 16. (Previously presented) A process according to claim 13 in which said plasma activation comprises an air plasma further including epoxy as an aerosol.